

PATENT 3811-0122P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

Yi Yeol LYU et al.

Conf.:

4059

Appl. No.:

10/621,380

Group:

1712

Filed:

July 18, 2003

Examiner: M. G. MOORE

For:

SILOXANE-BASED RESIN AND METHOD FOR

FORMING INSULATING FILM BETWEEN

INTERCONNECT LAYERS IN SEMICONDUCTOR

DEVICES BY USING THE SAME

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

February 4, 2005

Sir:

Transmitted herewith is a response to notice of non-compliant amendment in the above-identified application.

The enclose	ed document	is	being	trans	mitted	via	the	Certificate
of Mailing	provisions	of	37 C.	F.R.	§ 1.8.			

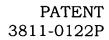
The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	12	-	20	=	0	\$50	\$0.00
INDEPENDENT	2	_	3	=	0	\$200	\$0.00
FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM							\$0.00
					· · · · · · · · · · · · · · · · · · ·	TOTAL	\$0.00

		month(s) extension of time pursuant to 1.136(a). \$0.00 for the extension of						
\boxtimes	No fee is required.							
	Check(s) in the amount of \$0.00 is(are) enclosed.							
	Please charge Deposit A \$0.00. This form is sub	Account No. 02-2448 in the amount of mitted in triplicate.						
over requ	urrent, and future repli payment to Deposit Accoun	ssioner is hereby authorized in this, ies, to charge payment or credit any nt No. 02-2448 for any additional fees 1.16 or under 37 C.F.R. § 1.17; ime fees.						
		Respectfully submitted,						
		BIRCH, STEWART, KOLASCH & BIRCH, LLF						
		By Not E Guerrer #42,593 For Joseph A. Kolasch, #22,463						
•		Joseph A. Kolasch, #22,463						
•	REG:jls -0122P	P.O. Box 747 Falls Church, VA 22040-0747 (703) 205-8000						

Attachment(s)





IN THE U.S. PATENT AND TRADEMARK OFFICE

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Examiner: Margaret G. Moore

For:

SILOXANE-BASED RESIN AND METHOD FOR

FORMING INSULATING FILM BETWEEN

INTERCONNECT LAYERS IN SEMICONDUCTOR

DEVICES BY USING THE SAME

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 February 4, 2005

Sir:

In reply to the Notice of Non-Complaint Amendment mailed January 28, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes a substitute claim set and remarks.